Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1-11. (Canceled)

12. (Currently Amended) A process for producing a recording medium molded in a form of a disk and having a recording layer, ~~and a~~ disk-shaped resin layer provided on said recording layer, and a hole at the center of said resin layer, said process comprising the steps of~~;~~:

forming ring-_shaped first and second concaves on a surface of said resin layer, said first and second concaves being formed with a center of said ~~recording medium~~hole as centers of said first and second concaves in concentric relation, ~~to form~~ an area between said first and second concaves ~~as~~ being a resin film formation area;

supplying a resin liquid containing a photopolymerizable resin onto said resin film formation area; and

curing said resin liquid layer to give a ridgy resin film raised above said surface of said resin layer.

13. (Currently Amended) A recording medium molded in a form of a disk and having a recording layer, ~~and a~~ disk-shaped resin layer provided on said recording layer, and a hole at the center of said resin layer, wherein:

_____ ring-_shaped first and second concaves ~~with a center of said recording medium as centers~~, a resin film formation area ~~between said first and second concaves~~, and a ridgy resin film ~~formed in said resin film formation area~~ are ~~formed~~ provided on a surface of said resin layer,

_____ said first and second concaves are provided with a center of said hole as centers of said first and second concaves in concentric relation,

_____said resin film formation area is constituted of a land between said first and second concaves, and

_____said ridgy resin film is provided onto said resin film formation area and raised above a̶ said surface of said resin layer.

14. (Original) The recording medium according to claim 13, wherein said resin layer is made of a polycarbonate resin.

15. (Previously Added) The recording medium according to claim 13, wherein said resin film formation area comprises a ridge on each of boundaries between said first concave and said resin film formation area and between said second concave and said resin film formation area.

16. (Previously Added) The recording medium according to claim 13, wherein a height from a surface of said resin film formation area to a surface of said ridgy resin film is 3μm or higher.

17. (Previously Added) The recording medium according to claim 13, wherein said ridgy resin film is formed by supplying a resin liquid to a surface of the resin formation area and curing said resin liquid.

18. (Previously Added) The recording medium according to claim 17, wherein a viscosity of said resin liquid at 25°C is 10mPa • s or higher and 1000mPa • s or lower.

19. (Previously Added) The recording medium according to claim 17, wherein a viscosity of said resin liquid at 25°C exceeds 100mPa • s.

20. (Previously Added) The recording medium according to claim 17, wherein said resin liquid contains photoreactive curable resin and said photoreactive curable resin is cured by irradiation of ultraviolet rays.

21. (Currently Amended) The recording medium according to claim 13, wherein said ridgy resin film comprises a resin of a glass transition ~~to~~ temperature which is 60°C or higher and below 100°C.

22. (New) The recording medium according to claim 13, wherein said ridgy resin film contains a resin selected from the group consisting of acrylic resin and epoxy resin.

23. (New) The recording medium according to claim 22, wherein said ridgy resin film contains an acrylic resin selected from the group consisting of epoxy acrylate, urethane acrylate, ester acrylate and melamine acrylate.

24. (New) The recording medium according to claim 22, wherein said ridgy resin film contains alicyclic epoxy resin as said epoxy resin.

25. (New) The recording medium according to claim 13, wherein a resin selected from the group consisting of polyethylene resin, acrylonitrile-butadiene-styrene and polycarbonate is used as a material of said resin layer.